

ABSTRACT

A method of manufacturing a wafer assembly comprising a chip wafer onto which a cover wafer is deposited, the chip wafer comprising an active face and an inactive face, the active face comprising chip elements, the cover wafer being provided with a chip-element-receiving cavity located above a chip element, comprises the following steps: - a cover-wafer-depositing step, in which a cover wafer is deposited on the active face so as to obtain a wafer assembly, the cover wafer being provided with a plurality of chip-receiving cavities, a chip-receiving cavity being located above a chip element, the cover wafer being made of an organic material; - a wafer assembly thinning step, in which the inactive face of the chip wafer is thinned; - an assembling step, in which a chip is placed in the cavity of the cover wafer stacked above the chip wafer.